

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the application:

Claims 1-7 (Canceled).

8. (New) A method of manufacturing semiconductor light-emitting devices comprising:

a step of mounting semiconductor light-emitting elements on one ends of leads arranged on a lead frame as a plurality of pairs in a straight line and at uniform spacing;

a step of connecting the semiconductor light-emitting elements to one ends of the others of the pairs of leads by bonding wires;

a step of immersing the semiconductor light-emitting elements, the bonding wires, and the one end of the leads in light-transmitting resin filled respectively into cavities of an envelope adjusting jig having the cavities positionally arranged in a straight line of the lead frame at the same spacing;

a step of curing the light-transmitting resins respectively; and

a step of removing each of the light-transmitting resins from the cavities and separating the pairs of leads from the lead frame;

wherein the each of the cavities has oblong, specifically lateral cross-sections by an ellipse and almost U-shaped longitudinal cross-section on the lead frame, a long axis of the lateral cross-section of the cavities is perpendicular to a lateral straight line as extending through the lead frame.

9. (New) The method of manufacturing semiconductor light-emitting devices as claimed in claim 8, wherein the envelope adjusting jig have cavities arranged in rows so that the cavities in one row are alternately offset and positioned at the midpoint of the spacing of the cavities in another row in the longitudinal direction.

10. (New) A semiconductor light-emitting device comprising:

- at least two parallel leads having adjacent distal ends;
- a semiconductor light-emitting chip mounted on the distal end of one of said leads;
- a bonding wire for electrically connecting the semiconductor light-emitting chip and the distal end of another of the at least two leads; and
- a light transmitting resin, for sealing said semiconductor light-emitting chip, said bonding wire, and the distal ends of said leads, the light transmitting resin having a side surface defined in lateral cross section by an ellipse having a long axis and a short axis, the side surface having oblong, specifically lateral cross-sections by an ellipse and almost U-shaped longitudinal cross-section on the lead frame, the long axis being perpendicular to a lateral straight line as extending through said at least two parallel

leads, and a convex external end surface for transmitting light from the semiconductor light-emitting chip to the exterior of the light transmitting resin.

11. (New) A semiconductor light-emitting device produced by a method comprising:

a step of mounting semiconductor light-emitting elements on one ends of leads arranged on a lead frame as a plurality of pairs in a straight line and at uniform spacing;

a step of connecting the semiconductor light-emitting elements to one ends of the others of the pairs of leads by bonding wires;

a step of immersing the semiconductor light-emitting elements, the bonding wires, and the one end of the leads in light-transmitting resin filled respectively into cavities of an envelope adjusting jig having the cavities positionally arranged in a straight line of the lead frame at the same spacing;

a step of curing the light-transmitting resins respectively; and

a step of removing each of the light-transmitting resins from the cavities and separating the pairs of leads from the lead frame;

wherein the each of the cavities has oblong, specifically elliptical lateral cross-sections and almost U-shaped longitudinal cross-section on the lead frame, a long axis of the lateral cross-section of the cavities is perpendicular to a lateral straight line as extending through the lead frame.

12. (New) The semiconductor light-emitting devices as claimed in claim 11, wherein the envelope adjusting jig have cavities arranged in rows so that the cavities in one row are alternately offset and positioned at the midpoint of the spacing of the cavities in another row in the longitudinal direction.